SWITCHMODE™ Schottky Power Rectifier

The SWITCHMODE Power Rectifier employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlay contact. Ideally suited for use as rectifiers in very low-voltage, high-frequency switching power supplies, free wheeling diodes and polarity protection diodes.

Features

- Highly Stable Oxide Passivated Junction
- Very Low Forward Voltage Drop
- Matched Dual Die Construction
- High Junction Temperature Capability
- High dv/dt Capability
- Excellent Ability to Withstand Reverse Avalanche Energy Transients
- Guardring for Stress Protection
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Electrically Isolated. No Isolation Hardware Required.
- Pb-Free Package is Available*

Mechanical Characteristics:

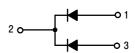
- Case: Epoxy, Molded
- Weight: 1.9 Grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead Temperature for Soldering Purposes: 260°C Max. for 10 Seconds



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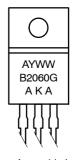
SCHOTTKY BARRIER RECTIFIER 20 AMPERES, 60 VOLTS





ISOLATED TO-220 CASE 221D STYLE 3

MARKING DIAGRAM



= Assembly Location

= Year WW = Work Week B2060 = Device Code = Pb-Free Package G = Polarity Designator

ORDERING INFORMATION

Device	Package	Shipping
MBRF2060CT	TO-220FP	50 Units/Rail
MBRF2060CTG	TO-220FP (Pb-Free)	50 Units/Rail

^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS (Per Leg)

Rating			Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V _{RRM} V _{RWM} V _R	60	V
Average Rectified Forward Current (Rated V_R), $T_C = 133^{\circ}C$	Total Device	I _{F(AV)}	10 20	Α
Peak Repetitive Forward Current (Rated V _R , Square Wave, 20 kHz), T _C = 133°C		I _{FRM}	20	Α
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions halfwave, single phase, 60 Hz)		I _{FSM}	150	Α
Peak Repetitive Reverse Surge Current (2.0 μs, 1.0 kHz)		I _{RRM}	0.5	Α
Operating Junction and Storage Temperature Range (Note 1)		T _J , T _{stg}	- 65 to +175	°C
Voltage Rate of Change (Rated V _R)		dv/dt	10000	V/μs
RMS Isolation Voltage (t = 0.3 second, R.H. ≤ 30%, T _A = 25°C) (Note 2)	Per Figure 3	V _{iso1}	4500	٧

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS (Per Leg)

Rating	Symbol	Value	Unit
Maximum Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	4.0	°C/W
Lead Temperature for Soldering Purposes: 1/8 in from Case for 5 Seconds	TL	260	°C

ELECTRICAL CHARACTERISTICS (Per Leg)

Characteristic	Symbol	Max	Unit
Maximum Instantaneous Forward Voltage (Note 3)	v _F		V
$(i_F = 10 \text{ Amp, } T_C = 25^{\circ}C)$		0.85	
$(i_F = 10 \text{ Amp, T}_C = 125^{\circ}\text{C})$		0.75	
$(i_F = 20 \text{ Amp, } T_C = 25^{\circ}C)$		0.95	
(i _F = 20 Amp, T _C = 125°C)		0.85	
Maximum Instantaneous Reverse Current (Note 3)	i _R		mA
(Rated DC Voltage, $T_C = 25^{\circ}C$)		0.15	
(Rated DC Voltage, T _C = 125°C)		150	

- 1. The heat generated must be less than the thermal conductivity from Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.
- 2. Proper strike and creepage distance must be provided.
- 3. Pulse Test: Pulse Width = 300 µs, Duty Cycle ≤ 2.0%

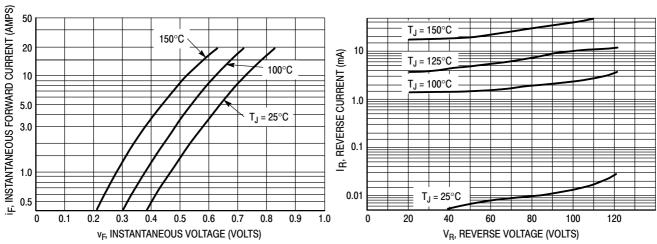


Figure 1. Typical Forward Voltage Per Diode

Figure 2. Typical Reverse Current Per Diode

TEST CONDITION FOR ISOLATION TEST*

FULLY ISOLATED PACKAGE

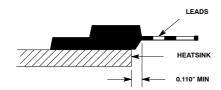
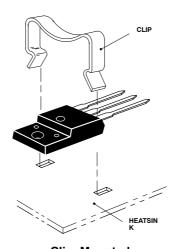


Figure 3. Mounting Position

*Measurement made between leads and heatsink with all leads shorted together.

MOUNTING INFORMATION

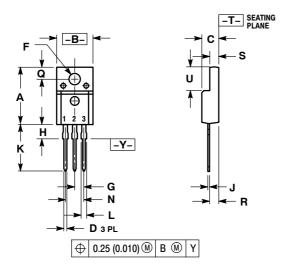


Clip-Mounted

Figure 4. Typical Mounting Technique

PACKAGE DIMENSIONS

TO-220 FULLPAK CASE 221D-03 **ISSUE K**



NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH 221D-01 THRU 221D-02 OBSOLETE, NEW STANDARD 221D-03.

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.617	0.635	15.67	16.12
В	0.392	0.419	9.96	10.63
С	0.177	0.193	4.50	4.90
D	0.024	0.039	0.60	1.00
F	0.116	0.129	2.95	3.28
G	0.100	0.100 BSC		BSC
Н	0.118	0.135	3.00	3.43
J	0.018	0.025	0.45	0.63
K	0.503	0.541	12.78	13.73
L	0.048	0.058	1.23	1.47
N	0.200 BSC		5.08 BSC	
Q	0.122	0.138	3.10	3.50
R	0.099	0.117	2.51	2.96
S	0.092	0.113	2.34	2.87
U	0.239	0.271	6.06	6.88

STYLE 3:

PIN 1. ANODE CATHODE 3. ANODE

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